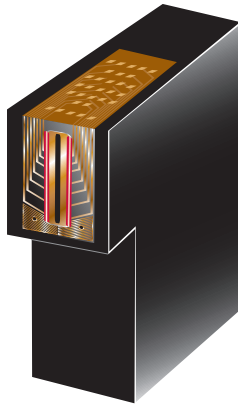


## Circuit Assembly – Non-Conductive



- **Flex Circuits**
- **Camera Modules**
- **Printer Heads**
- **Smart Cards**

PRODUCT	DESCRIPTION	VISCOSITY 19 s <sup>-1</sup> (cP)	T <sub>g</sub> , TAN δ (°C)	CURE SCHEDULE	POT LIFE @ 25°C (hr)
<b>Chip on Board Encapsulants</b>					
EN-7826	Glob top encapsulant. User friendly pot life (> 2 days), superior environmental protection with enhanced moisture resistance and internal stress relief. CTE α <sub>1</sub> (<T <sub>g</sub> ) ≈ 18ppm/°C	65,000	140	30 min @ 150°C	>48
DE-7826	Dam fill material. Matches cavity properties. User friendly pot life (>2 days), superior environmental protection with enhanced moisture resistance and internal stress relief. CTE α <sub>1</sub> (<T <sub>g</sub> ) ≈ 18ppm/°C	200,000	140	30 min @ 150°C	>48
CE-7826	Cavity fill material. Matches dam properties. Excellent flow properties, user friendly pot life (> 2 days), superior environmental protection with enhanced moisture resistance and internal stress relief. CTE α <sub>1</sub> (<T <sub>g</sub> ) ≈ 18ppm/°C	40,000	140	30 min @ 150°C	>48
<b>UV Cure Chip Encapsulants</b>					
DC-4261	Material for chip encapsulation. Good for smart cards and general circuit assembly applications	10,000	112	UV and/or 30 min @ 150°C	72
<b>Flex Circuit / Printer Head Assembly Adhesives and non-conductive die attach</b>					
DA-5801	White, low viscosity adhesive, encapsulant, bonding FR4 to kapton, high fracture toughness, high ink and moisture resistance	20,000	60	60 min @ 80°C 3 min @ 150°C	72
357-284	White, high thixotropy adhesive, encapsulant, bonding FR4 to kapton and stainless steel high fracture toughness, high ink and moisture resistance	110,000	65	40 min @ 80°C 1 min @ 150°C	72
357-348	White, low viscosity adhesive, encapsulant, bonding FR4 to kapton, high fracture toughness, high ink and moisture resistance	9,500	50	60 min @ 80°C 5 min @ 150°C	72
332-5-122	Moderate T <sub>g</sub> , hydrophobic, high strength adhesive for circuit assembly and printer head assemblies. Can withstand harsh environments, solvent resistant	25,000	106	30 min @ 120°C	72
EN-7930	Low viscosity, electrically insulating die attach adhesive	3,500	50	60 min @ 80°C 15 min @ 120°C	48
<b>R&amp;D</b> DA-5310	Screen printable B stage adhesive for die/component attach. Tack-free after B-stage. Die/component can be staked & cured simultaneously	16,000	132	60 min @ 160°C	24
<b>Camera Module Assembly Adhesives for Lens Holder Assembly</b>					
631-188-3	High T <sub>g</sub> , low CTE α <sub>1</sub> (<T <sub>g</sub> ) ≈ 18ppm/°C, dimensionally stable dual cure for photonic, camera module and general electronics assembly applications	48,000	150	UV and/or 60 min @ 120°C	24